

For immediate release

January 30, 2009

Name of the Company: MegaChips Corporation  
Representative: Yukihiro Ukai  
President and Representative  
Director  
(Code No. 6875, the First Section of the Tokyo Stock Exchange)  
Person to contact: Masayuki Fujii  
Director, Officer and General Manager  
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### **Notice regarding Change in Organization and Executive Personnel**

MegaChips Corporation resolved at the Board of Directors Meeting held on January 30, 2009 the change in organization and executive personnel as follows:

#### **1. Purpose of changing organization and executive personnel**

In this unprecedented global recession that stemmed from the financial turmoil, MegaChips Corporation sees it big opportunity rather than the crisis. The structural reform reflects the company's intention to further expand its business, pushing forward with its customer-focused business, and capitalizing on its technological strengths in LSI and System to offer a wide range of optimum solutions.

#### **2. Details of organization change**

- (1) MegaChips Corporation will establish new Business Headquarters by the consolidation of the Customer Specific Business Headquarters and Specific Use Business Headquarters.  
By offering distinctive products through a variety of concepts and contributing to customers' businesses, the Company will find paths for further growth.
- (2) MegaChips Corporation will establish System Business Division, LSI Business Division No. 1, LSI Business Division No. 2, Electronic Device & Module Business Division and a Sales Division, all within the Business Headquarters.
- (3) The System Business Division will operate system products specialized in customer-specific uses.
- (4) The LSI Business Divisions No. 1 and 2 will promote business related to LSI products that are specialized for customers' devices.
- (5) The Electronic Device & Module Business Division will operate business related to board module products that feature Company's system LSI. The Divisions will capitalize on the distinctive products for the electronic devices to develop a new business associated with the environment and energy conservation.
- (6) For the purpose of promoting alliance business more aggressively, the Strategic Management Office will be changed to the Strategic Alliance Office.

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### 3. Details of New Executive Personnel

Name of new position	Name	Name of current position
Executive Vice President, General Manager of Business Headquarters, Department Manager of Sales Division	Yoshimasa Hayashi	Executive Director, Executive, General Manager of Customer Specific Business Headquarters
Executive Vice President, General Manager of Administrative Headquarters	Shigeki Matsuoka	Vice President and Representative Director, General Manager of Administrative Headquarters
Director, Officer, General Manager of Electronic Device & Module Business Division at Business Headquarters	Keizo Higuchi	Director, Officer, General Manager of Specific Use Business Headquarters, General Manager of ASSP Business Division
Officer, General Manager of Strategic Alliance Office at Administrative Headquarters	Akira Takata	Officer, General Manager of Strategic Management Office at Administrative Headquarters
Officer, General Manager of LSI Business Division No. 2 at Business Headquarters	Tetsuo Hikawa	Officer in charge of New Customer Development at Customer Specific Business Headquarters, Department Manager of New Customer Development Division
Officer, General Manager of LSI Business Division No. 1 at Business Headquarters	Tetsuo Furuichi	Officer, General Manager of ASIC Business Division at Customer Specific Business Headquarters
Officer, General Manager of System Business Division at Business Headquarters, Head of Tokyo Office	Shunsuke Shikata	Officer, General Manager of System Business Division at Customer Specific Business Headquarters, Head of Tokyo Office
Assistant General Manager of Electronic Device & Module Business Division at Business Headquarters	Takashi Furumura	Officer, General Manager of Module & Electronic Device Division at Specific Use Business Headquarters

End of notice

(Attachment)

Structure effective February 1, 2009

